

CUSTOMER: _____

DATE: _____

APPROVAL SPECIFICATION

PRODUCT NAME: SMD power inductor

YOUR PART NO. :

OUR PART NO. : MGSFD4D22-100M-LF

VERSION: V1.0

<p>RECEPTION</p> <p>THE SPECIFICATION HAS BEEN ACCEPTED.</p> <p style="text-align: right;">DATE:</p> <p>COMPANY:</p>		
CFMD	CHKD	RCVD

MANUFACTURING NAME

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CFMD.	CHKD.	DSGD.
Charles	王玉生	刘维

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Component SPEC Version Record

Rev.	Effective Date	Changed Contents	Change Reasons	Approved By
1.0	Dec. 10.2012	New released	/	Charles

1. Scope

This specification applies to the MGSFD series of SMD power inductor.

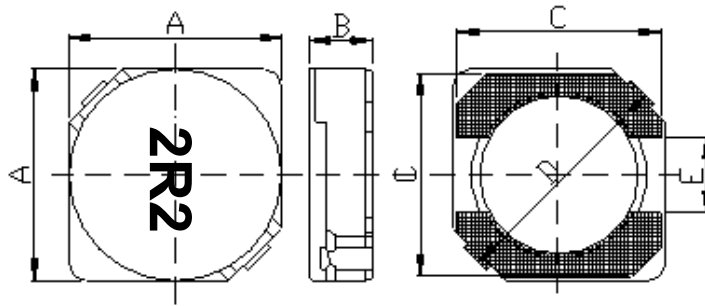
2. Product Identification

MGSFD 4D22 - 4R7 N - LF
① ② ③ ④ ⑤

- ① Product Symbol
- ② Product dimensions
- ③ Inductance Value: (4R7: 4.7uH 100: 10uH; 101: 100uH)
- ④ Inductance Tolerance: (K:10% ; M:20% ;N:30%)
- ⑤ Lead free product.

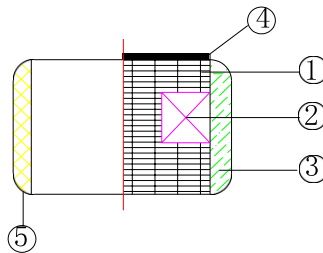
3. Appearance, Dimensions and Material

3.1 Appearance and dimensions



Dimensions in mm					
Model	A	B	C	D	E
MGSFD4D22	4.7±0.3	2.5 max	5.3typ	6.9 max.	1.5ref

3.2 Material List



No.	Part name	Material	Ceaiya P/N
①	Drum Core	Ni-Zn Ferrite Core	(RL B1.2)
②	Wire	Polyurethane enameled copper wire	9310100
③	Ring Core	Ni-Zn Ferrite Core	(RL)
④	Adhesive	Epoxy Resin	7001007(001)
⑤	Electrode	Cu + Sn plating	(LC)

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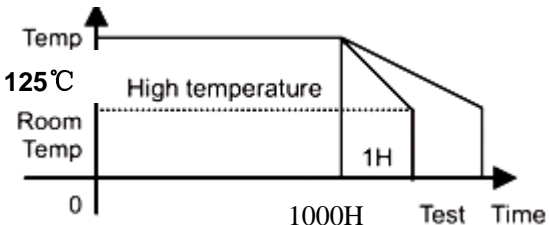
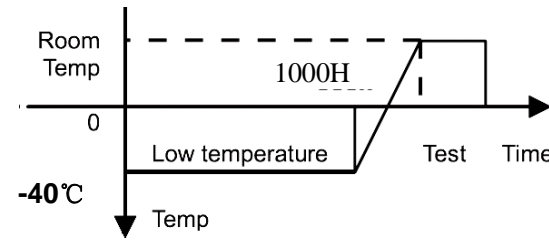
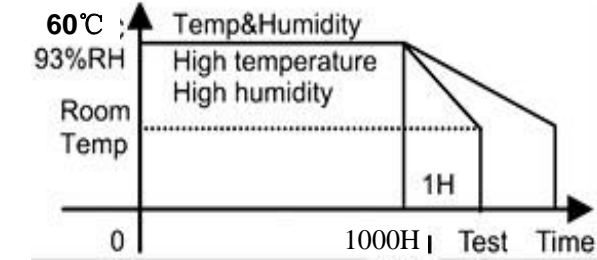
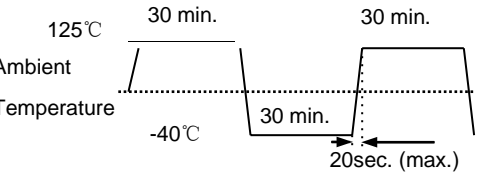
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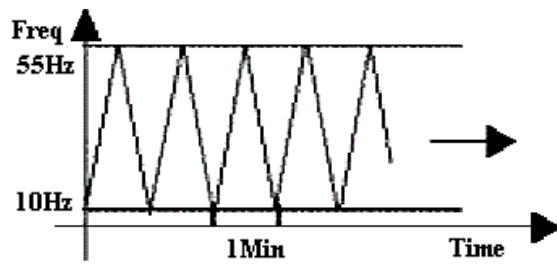

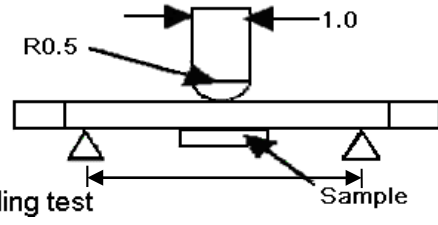
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7. Reliability and Test Condition

Item	Required Characteristics	Test Method/Condition
High temperature resistance		<p>Temperature: 125±2 °C Time : 1000 hours Tested not less than 1 hours, nor more than 2 hours at room temperature.</p> 
Low temperature resistance	<ol style="list-style-type: none"> No case deformation or change in appearance. $\Delta L /L \leq 10\%$ 	<p>Temperature : -40±2 °C Time : 1000 hours Tested not less than 1 hour, nor more than 2 hours at room temperature.</p> 
Humidity test		<ol style="list-style-type: none"> Exposure : Temperature:60±2 °C, Humidity : 93±3% RH Time : 1000 hours. Tested while the specimens are still in the chamber. Tested not less than 1 hour, nor more than 2 hours at room temperature. 
Thermal shock test	<ol style="list-style-type: none"> No case deformation or change in appearance. $\Delta L /L \leq 10\%$ 	<p>First -40°C for T time, last 125°C T time as 1 cycle. Go through 100 cycles.</p> 

Item	Required Characteristics	Test Method/Condition
Solderability test	Terminal area must have 90% min. solder coverage.	Dip pads in flux then dip in solder pot at $245 \pm 5^\circ\text{C}$ for < 5 second. Solder: lead free Flux: rosin flux.
Heat endurance of reflow soldering		Refer to the next page reflow curve Go through 3 times. The peak temperature: $260+5/-0^\circ\text{C}$
Vibration test	1. No case deformation or change in appearance. 2. $ \Delta L /L \leq 10\%$	Apply frequency 10~55Hz. 1.5mm amplitude in each of perpendicular direction for 2 hours in each 3 mutually perpendicular directions.(total 6 hours) 
Drop test		Packaged & drop down from 1m with $981\text{m/s}^2(100\text{G})$ attitude in 1 angle 1 ridges & 2surfaces orientations.
Terminal strength push test	Pulling test: Define: Solder the products on testing PCB using eutectic solder. Then apply a force in the direction of the arrow. 10N force. Keep time $\geq 5\text{s}$ Bending test: Soldering the products on PCB, after the pulling test and bending test, terminal should not pull off.	Bend the testing PCB at middle point, the deflection shall be 2mm. Pressurizing Speed: 0.5mm/sec, Keep time: $30 \pm 1\text{s}$, Pulling test  Bending test 
Resistance to solvent test	No case deformation or change in appearance, or obliteration of marking	To dip parts into IPA solvent for 50.5Min, then drying them at room temp for 5Min., at last, to brushing marking 10 times.
Loading Under Humidity Heat	1. No case deformation or change in appearance. 2. $ \Delta L /L \leq 10\%$	1. Exposure : Temperature: $60 \pm 2^\circ\text{C}$, Humidity : $93 \pm 3\%$ RH Time : 1000 hours. Apply rated current 2. Tested while the specimens are still in the chamber. 3. Tested not less than 1 hour, nor more than 2 hours at room temperature.
Loading at High Temperature	1. No case deformation or change in appearance. 2. $ \Delta L /L \leq 10\%$	1. Temperature: $85 \pm 2^\circ\text{C}$ 2. Time : 1000 hours 3. Apply rated current 4. Tested not less than 1 hours, nor more than 2 hours at room temperature.

8. Recommended Soldering Conditions

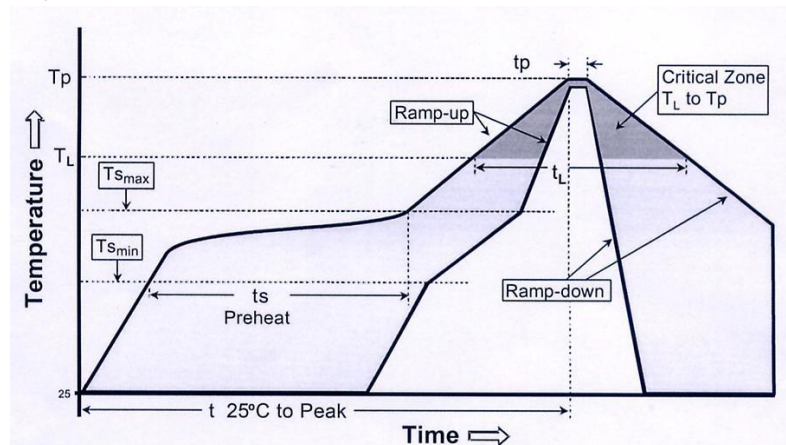
Product can be applied to flow and reflow soldering.

(1) Flux, Solder

- ① Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).
- ② Use Sn solder.

(2) Reflow soldering conditions

Reflow curve



Profile Feature		Lead-Free Assembly
Average Ramp-Up Rate (Ts max. to Tp)		3°C /second max.
Preheat	- Temperature Min (Ts min.)	150 °C
	- Temperature Max (Ts max.)	200 °C
	- Time (ts min to ts max.)	60-180 seconds
Time maintained above	- Temperature (TL)	217 °C
	- Time (tL)	60-150 seconds
Peak/Classification Temperature (Tp)		260 °C
Peak/Classification Time (Tp)		10 seconds
Time within 5 °C of actual Peak Temperature (Tp)		20-40 seconds
Ramp-Down Rate		6°C/second max.
Time 25 °C to Peak Temperature		8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

(3) The method on Re-work with using the iron:

The following conditions must be strictly followed when using a soldering iron

Pre-heating	150°C, 1 minute
Tip temperature	350°C max
Soldering iron output	80w max
End of soldering iron	φ1mm max
Soldering time	3 seconds max

Product once removes from the circuit board may not be used again.

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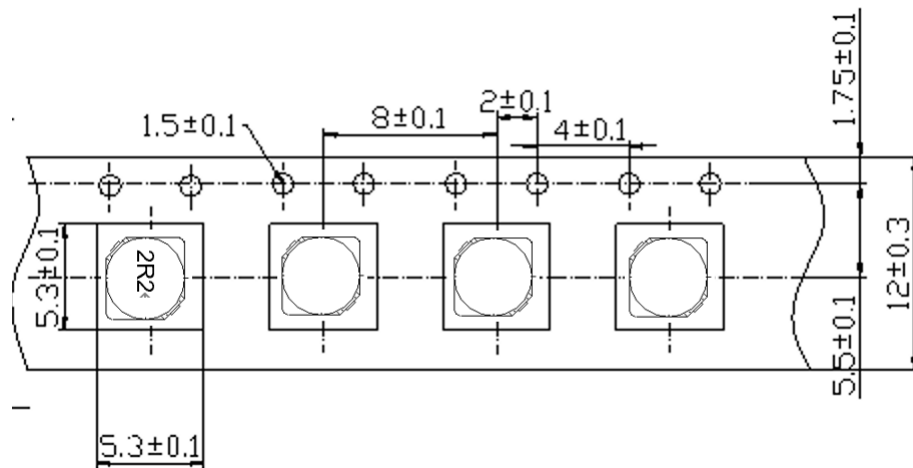
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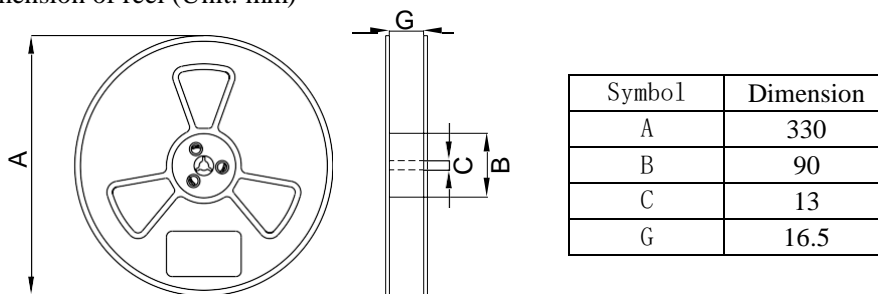
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9. Package Information

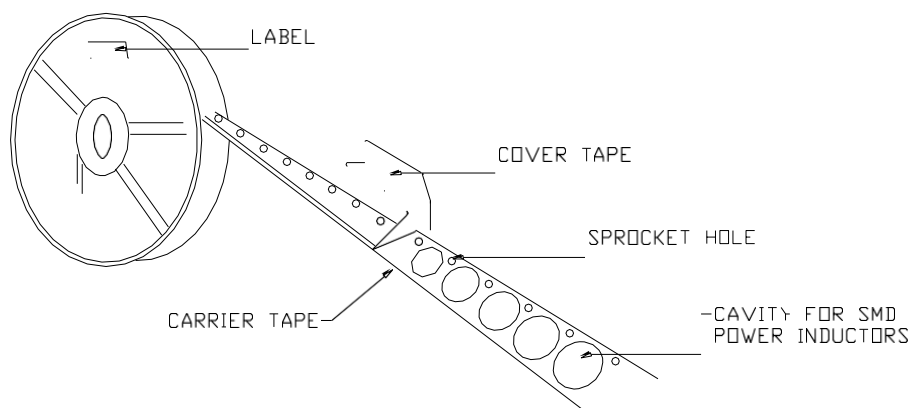
9.1 Dimension of tape (Unit: mm)



9.2 Dimension of reel (Unit: mm)



9.3 Taping figure and drawing direction



9.4 Packaging quantities: 2000PCS/Reel.

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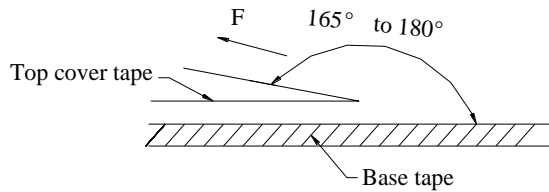
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9.5 Peeling strength of cover tape:

The peel force of top cover tape shall be between 0.15N to 0.65N



Room Temp. (°C)	Room Humidity (%)	Room aim (hpa)	Peel Speed Mm/min
5-35	45-85	860-1060	300

10. Products Storage

(1) Storage period

Products which inspected in MICROGATE over 6 months ago should be examined and used, which can be confirmed with inspection No. marked on the container. Solderability should be checked if this period is exceeded.

(2) Storage conditions

Products should be storage in the warehouse on the following conditions:

Temperature: -10 ~+ 40°C

Humidity : Less than 80% relative and humidity

No rapid change on temperature and humidity

- (3) Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.
- (4) Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.
- (5) Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- (6) Products should be storage under the airtight packaged condition.

单击下面可查看定价，库存，交付和生命周期等信息

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